



SLOVENSKI STANDARD
oSIST prEN 16602-60-13:2021

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Nadomešča:

SIST EN 16602-60-13:2015

Zagotavljanje varnih proizvodov v vesoljski tehniki - Zahteve za uporabo COST-komponent

Space product assurance - Commercial electrical, electronic and electromechanical (EEE) components

Raumfahrtproduktsicherung - Anforderungen für die Nutzung von COTS-Komponenten

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Assurance produit des projets spatiaux - Exigences pour l'utilisation de composants commerciaux sur étagère

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EUROPEAN STANDARD
NORME EUROPÉENNE
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Space product assurance - Commercial electrical, electronic and electromechanical (EEE) components

Assurance produit des projets spatiaux - Exigences
pour l'utilisation de composants commerciaux sur
étagère

Raumfahrtproduktsicherung - Anforderungen für die
Nutzung von COTS-Komponenten

This draft European Standard is submitted to CEN members for enquiry. It has been drawn up by the Technical Committee CEN/CLC/JTC 5.

If this draft becomes a European Standard, CEN and CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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Table of contents

European Foreword.....	5
Introduction.....	6
1 Scope.....	8
2 Normative references	9
3 Terms, definitions and abbreviated terms.....	11
3.1 Terms from other standards.....	11
3.2 Terms specific to the present standard	11
3.3 Abbreviated terms.....	11
3.4 Conventions.....	13
3.5 Nomenclature	14
4 Requirements for class 1 components.....	15
5 Requirements for class 2 components.....	35
6 Requirements for class 3 components.....	53
7 Quality levels	70
8 Procurement test table.....	71
9 Pure tin lead finish – risk analysis	109
Annex A (normative) Component control plan (CCP) - DRD	110
Annex B (normative) Declared components list (DCL) - DRD	111
Annex C (normative) Internal Supplier’s specification - DRD.....	112
Annex D (normative) Parts approval document - DRD.....	113
Annex E (informative) EEE documents delivery per review	114
Annex F (normative) Justification document - DRD	115
Annex G <<deleted>>	118
Annex H (informative) Flow chart for construction analysis and destructive physical analysis.....	119

Bibliography..... 123**Figures**

Figure 4-1: <<deleted>>	23
Figure 4-2: <<deleted>>	28
Figure 5-1: <<deleted>>	42
Figure 5-2: <<deleted>>	47
Figure 6-1: <<deleted>> Lot acceptance test flow chart for Class 3 components	64
Figure 8-1: <<deleted>>	71
Figure 8-2: <<deleted>>	71
Figure 8-3: <<deleted>>	71
Figure 8-4: <<deleted>>	71
Figure 8-5: <<deleted>>	71
Figure 8-6: <<deleted>>	72

Tables

Table 4-1: <<deleted and moved as legacy test files as Table 8-9>>	24
Table 4-2: <<deleted and moved as legacy test files as Table 8-10>>	27
Table 4-3: <<deleted and moved as legacy test files as Table 8-11>>	28
Table 4-4: Documentation for Class 1 components	34
Table 5-1: <<deleted and moved as Legacy test files as Table 8-12>>	42
Table 5-2: <<deleted and moved as Legacy test files as Table 8-13>>	46
Table 5-3: <<deleted and moved to Legacy test files as Table 8-14>>	47
Table 5-4: Documentation for Class 2 components	52
Table 6-1: <<deleted>>	60
Table 6-2: <<deleted>>	63
Table 6-3: <<deleted and moved as Legacy test files Table 8-15>>	64
Table 6-4: Documentation for Class 3 components	69
Table 8-1: Procurement test table for ceramic capacitors chips	74
Table 8-2: Procurement test table for solid electrolyte tantalum capacitors chips.....	75
Table 8-3: Procurement test table for discrete parts (diodes, transistors, optocouplers)	78
Table 8-4: Procurement test table for fuses	80
Table 8-5: Procurement test table for magnetics.....	81
Table 8-6: Procurement test table for microcircuits	84
Table 8-7: Procurement test table for resistors	85
Table 8-8: Procurement test table for Thermistors	88
Table 8-9: Legacy test files - Evaluation tests for Class 1 components.....	90

prEN 16602-60-13:2021 (E)

Table 8–10: Legacy test files - Screening tests for Class 1 components	93
Table 8–11: Legacy test files - Lot acceptance tests for Class 1 components	95
Table 8–12: Legacy test files - Evaluation tests - Class 2 components.....	98
Table 8–13: Legacy test files - Screening tests - Class 2 components	101
Table 8–14: Legacy test files - Lot acceptance tests - Class 2 components	103
Table 8–15: Legacy test files - LAT tests - Class 3 components.....	106
Table H-1 : Construction analysis sequence.....	120

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European Foreword

This document (prEN 16602-60-13:2021) has been prepared by Technical Committee CEN/CLC/TC 5 "Space", the secretariat of which is held by DIN (Germany).

This document (prEN 16602-60-13:2021) originates from ECSS-Q-ST-60-13C Rev.1 DIR1.

This document is currently submitted to the ENQUIRY.

This document will supersede EN 16602-60-13:2015.

The main changes with respect to EN 16602-60-13:2015 are listed below:

- to be completed (currently the changes are identified with revision tracking).

This document has been developed to cover specifically space systems and will therefore have precedence over any EN covering the same scope but with a wider domain of applicability (e.g. : aerospace).

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Introduction

This standard is based on and complementary to ECSS-Q-ST-60C (with upward revisions). This standard can only be used in conjunction with ECSS-Q-ST-60C in its current revision. This standard applies only to commercial components - as defined in its scope - which meet defined technical parameters that are on the system application level demonstrated to be unachievable with existing space components or only achievable with qualitative and quantitative penalties. The standard requires that qualitative and quantitative penalties are specified, as applicable, as a minimum in terms of quantifiable parameters such as: functional capability, parts count, power dissipation, frequency of operation, data/signal processing efficiency, interconnect complexity, mass, volume, ...

For traceability to ECSS-Q-ST-60, the modifications or additions are marked in blue. Text in black colour is unmodified text.

The objective of the EEE component selection, control, procurement and use requirements is to ensure that EEE components used in a space project enables the project to meet its mission requirements.

Important elements of EEE component requirements include:

- a. component programme management,
- b. component selection, evaluation and approval,
- c. procurement,
- d. handling and storage,
- e. component quality assurance,
- f. specific components, and
- g. documentation.

The main tools which can be used to reach the objective are:

- a. concurrent engineering,
- b. standardization of component types,
- c. characterization of components,
- d. assessment of component manufacturers including declared competencies and processes,
- e. testing, screening, lot acceptance and periodic testing,
- f. procurement specifications,
- g. control and inspection,
- h. control of nonconforming materials,
- i. assessment and use of existing component data,
- j. application of specific control to mitigate risk for components with limited data or confidence, and
- k. information management.

The basic approach is as follows:

- The customer of a given space project defines the EEE component requirements within the boundaries of this standard. They appear in the appropriate clauses of the project requirements as defined in ECSS-M-ST-10.

- The supplier defines a component control plan to implement those requirements into a system which enables, for instance, to control the selection, approval, procurement, handling in a schedule compatible with his requirements, and in a cost-efficient way.
- The supplier ensures that the applicable parts requirements are passed down to lower level suppliers and ensure that they are compliant to these parts requirements.

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1

Scope

This standard defines the requirements for selection, control, procurement and usage of EEE commercial components for space projects.

This standard is applicable to commercial parts from the following families:

- Ceramic capacitors chips
- Solid electrolyte tantalum capacitors chips
- Discretes parts (transistors, diodes, optocouplers)
- Fuses
- Magnetic parts
- Microcircuits
- Resistors
- Thermistors

Other families of EEE components are not addressed by the present ECSS standard doesn't mean that they are forbidden in commercial grade.

In line with ECSS-Q-ST-60, this standard differentiates between three classes of components through three different sets of standardization requirements (clauses) to be met.

The three classes provide for three levels of trade-off between assurance and risk. The highest assurance and lowest risk is provided by class 1 and the lowest assurance and highest risk by class 3. Procurement costs are typically highest for class 1 and lowest for class 3. Mitigation and other engineering measures can decrease the total cost of ownership differences between the three classes. The project objectives, definition and constraints determine which class or classes of components are appropriate to be utilised within the system and subsystems.

- a. Class 1 components are described in Clause 4
- b. Class 2 components are described in Clause 5
- c. Class 3 components are described in Clause 6

The requirements of this document are applicable to all parties involved at all levels in the integration of EEE commercial components into space segment hardware and launchers.

For easy tailoring and implementation of the requirements into a Requirement Management Tool, and for direct traceability to ECSS-Q-ST-60, requirements in this standards have been written in the way of a ECSS Applicability Requirement Matrix (EARM), as defined in Annex A of ECSS-S-ST-00 "ECSS system – Description, implementation and general requirements".

This standard may be tailored for the specific characteristics and constrains of a space project in conformance with ECSS-S-ST-00.

2

Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this ECSS standard. For dated references, subsequent amendments to, or revision of any of these publications do not apply. However, parties to agreements based on this ECSS Standard are encouraged to investigate the possibility of applying the more recent editions of the normative documents indicated below. For undated references, the latest edition of the publication referred to applies.

EN reference	Reference in text	Title
EN 16601-00-01	ECSS-S-ST-00-01	ECSS system - Glossary of terms
EN 16602-60	ECSS-Q-ST-60	Space product assurance - Electrical, electronic and electromechanical (EEE) components
EN 16602-60-14	ECSS-Q-ST-60-14	Space product assurance - Relifing procedure - EEE components
EN 16602-60-15	ECSS-Q-ST-60-15	Space product assurance - Radiation hardness assurance - EEE components
	ESCC 21300	Terms definitions, abbreviations, symbols and units
	ESCC 24900	Minimum requirements for controlling environmental contamination of components
	ESCC 25500	Methodology for the detection of pure tin in the external surface finish of case and leads of EEE components
	MIL-STD-750	Test methods for semiconductor devices
	MIL-STD-883	Test method standard microcircuits
	JESD22-A101	Steady state temperature humidity bias life test
	JESD22-A110	Highly accelerated temperature and humidity stress test
	JESD22-A113	Preconditioning of plastic surface mount devices prior to reliability testing
	JESD22-A121	Test Method for Measuring Whisker Growth on Tin and Tin Alloy Surface Finishes
	JESD22-B106	Resistance to soldering temperature for through hole mounted devices
	JESD-201	Environmental Acceptance Requirements for Tin Whisker Susceptibility of Tin and Tin Alloy Surface Finishes

prEN 16602-60-13:2021 (E)

	J-STD-020	Moisture/Reflow sensitivity classification for nonhermetic solid state surface mount devices
	J-STD-033	Handling, packing, shipping and use of moisture/reflow sensitive surface mount devices
	GEIA-STD-005-2	Standard for Mitigating the Effects of Tin Whiskers in Aerospace and High Performance Electronic Systems.
	ESCC 21004	GUIDELINES FOR INCOMING INSPECTION OF EEE COMPONENTS (ESCC Basic Specification No. 21004)
	ESCC25100	Single Event Effects Test Method and Guidelines
	ESCC22500	GUIDELINES FOR DISPLACEMENT DAMAGE IRRADIATION TESTING
	ESCC20600	Preservation Packaging and Despatch of SCC Components

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Terms, definitions and abbreviated terms

3.1 Terms from other standards

For the purpose of this standard, the terms and definitions from ECSS-S-ST-00-01 apply.

For the purpose of this standard, the following terms and definitions from ECSS-Q-ST-60 apply:

agent

characterization

commercial component

concurrent engineering

franchised distributor

parts engineer

parts procurer

qualified parts

screening

space qualified parts

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3.2 Terms specific to the present standard

3.2.1 traceability information (trace code)

unique identifier used by manufacturers to label and trace a quantity of components with a common manufacturing history and thereby common characteristics.

NOTE 1 The notion of "lot of EEE parts" used for the radiation and lot acceptance tests is defined by the trace code.

NOTE 2 Several trace codes can be part of a same delivery from the manufacturer or the distributor.

NOTE 3 It is possible to have several diffusion lots and wafer fabs (as per ESCC 21300) in the same trace code.

3.3 Abbreviated terms

For the purpose of this Standard, the abbreviated terms from ECSS-S-ST-00-01 and the following apply:

Abbreviation	Meaning
AOQ	average outgoing quality

prEN 16602-60-13:2021 (E)

Abbreviation	Meaning
ASIC	application specific integrated circuit
BGA	ball grid array
CA	construction analysis
CCD	charge coupled device
CCP	component control plan
CN	change notice
CoC	certificate of conformance
CDR	critical design review
CR	change request
DCL	declared components list
DPA	destructive physical analysis
DRD	document requirement definition
DSM	deep Sub-Micron
Ea	activation energy
ECSS	European Coordination for Space Standardization
EEE	electrical, electronic, electromechanical
EFR	early failure rate
ESCC	European space components coordination
GSE	ground support equipment
HAST	highly accelerated stress test
HTRB	high temperature reverse bias
JD	justification document
LAT	lot acceptance test
LED	light emitting diode
LVT	lot validation testing
MMIC	microwave monolithic integrated circuit
PAD	parts approval document
PCB	parts control board
PCN	process change notice
PDA	percent defective allowable
PED	plastic encapsulated device
PIND	particle impact noise detection
QBSD	full quadrant back scatter electron detector
QCI	quality conformance inspection
RFD	request for deviation
RH	relative humidity
RoHs	restriction of the use of certain hazardous substances

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Abbreviation	Meaning
RVT	radiation verification testing
SCSB	Space Components Steering Board
SAM	scanning acoustic microscopy
SEM	scanning electron microscope
SMD	surface mount device
TCI	technology conformance inspection
T _g	glassivation temperature
THB	temperature humidity bias
T _j	junction temperature
T/C	thermal cycling

3.4 Conventions

- a. The term "EEE component" is synonymous with the terms "EEE Part", "Component" or just "Part".
- b. The term "for approval" means that a decision of the approval authority is necessary for continuing the process.
- c. The term "for review" means that raised reviewers comments are considered and dispositioned.
- d. The term "for information" means that no comments are expected about the delivered item.
- e. For the purpose of clear understanding of this document, hereunder is a listing of component categories which are covered by the term EEE component, encapsulated or non-encapsulated, irrespective of the quality level:
1. Capacitors
 2. Connectors
 3. Crystals
 4. Discrete semiconductors (including diodes, transistors)
 5. Filters
 6. Fuses
 7. Magnetic components (e.g. inductors, transformers, including in-house products)
 8. Monolithic Microcircuits (including MMICs)
 9. Hybrid circuits
 10. Relays
 11. Resistors, heaters
 12. Surface acoustic wave devices